

N-Ch MOSFET

General Description

The WSF20N06 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF20N06 meet the RoHS and Green Product requirement.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

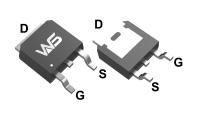
Product Summery

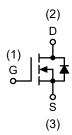
BVDSS	RDSON	ID
60V	35mΩ	25A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- LCD/LED back light

TO-252-2L Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	25	А
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	27	Α
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	8	А
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	10	Α
I _{DM}	Pulsed Drain Current ²	100	А
EAS	Single Pulse Avalanche Energy ³	38	mJ
I _{AS}	Avalanche Current	14	Α
P _D @T _C =25℃	Total Power Dissipation ⁴	35	W
P _D @T _A =25℃	Total Power Dissipation ⁴	3.3	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	℃

Thermal Data

Symbol	Parameter		Тур. Мах.	
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹		75	°C/W
Rejc	Thermal Resistance Junction-Case ¹		3	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25 $^{\circ}\mathbb{C}$, ID=1mA		0.057		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =16A		35	45	mΩ
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V _{GS} =5V , I _D =8A		40	50	
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/ -250uA	1.0	1.6	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.68		mV/℃
ı	Drain Source Leakage Current	V_{DS} =60V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =60V , V_{GS} =0V , T_J =125 $^{\circ}$ C			100	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 16V$, V_{DS} = $0V$			±10	nA
gfs	Forward Transconductance	V _{DS} =25V , I _D =18A		25		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7	3.4	Ω
Q_{g}	Total Gate Charge (4.5V)			20		
Q_gs	Gate-Source Charge	V_{DS} =30V , V_{GS} =10V , I_{D} =18A		7		nC
Q_gd	Gate-Drain Charge			5		
T _{d(on)}	Turn-On Delay Time			18		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		15		
T _{d(off)}	Turn-Off Delay Time	$R_G=6.8\Omega$, $I_D=1A$		60		ns
T _f	Fall Time			31		
Ciss	Input Capacitance			650		
C _{oss}	Output Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		95		pF
C _{rss}	Reverse Transfer Capacitance			60		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.1mH , I _{AS} =15A	19			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			25	Α
I _{SM}	Pulsed Source Current ^{2,6}	V _G -V _D -UV , Force Current			75	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =20A , T_{J} =25 $^{\circ}$ C			1.3	V
t _{rr}	Reverse Recovery Time	15 004 H/H 4004/ TJ 05°0		65		nS
Q _{rr}	Reverse Recovery Charge	IF=20A ,dI/dt=100A/μs,TJ=25℃		85		nC

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width $\leq \,$ 300us , duty cycle $\leq \,$ 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =15A
- 4.The power dissipation is limited by 150 $^{\circ}$ C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

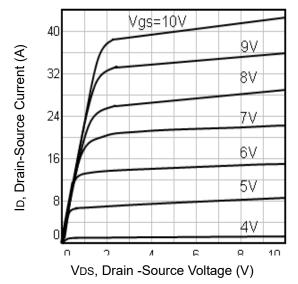


Fig1. Typical Output Characteristics

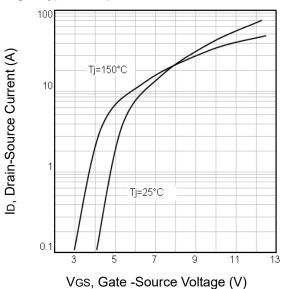


Fig3. Typical Transfer Characteristics

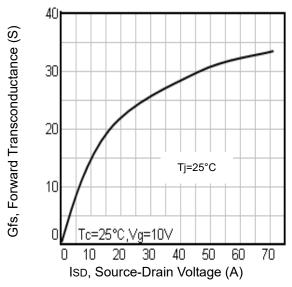
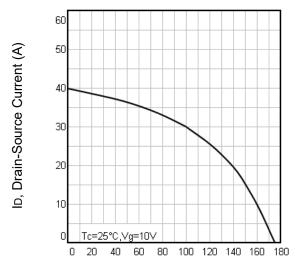


Fig5. Typical Forward Transconductance Vs. Drain Current



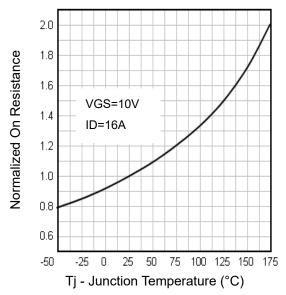


Fig4. Normalized On-Resistance Vs. Temperature

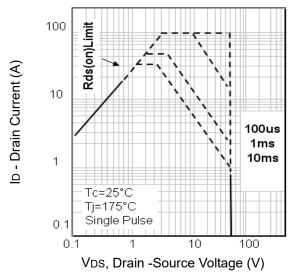


Fig6. Maximum Safe Operating Area



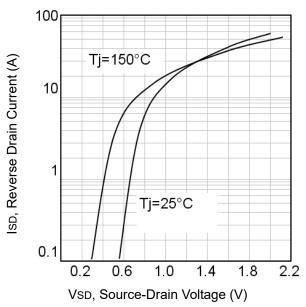


Fig7. Typical Source-Drain Diode Forward Voltage

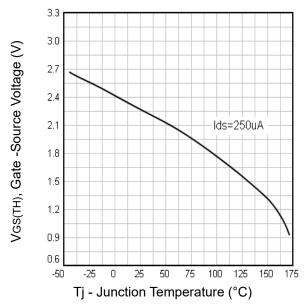


Fig9. Threshold Voltage Vs. Temperature

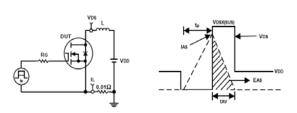


Fig11. Unclamped Inductive Test Circuit and waveforms

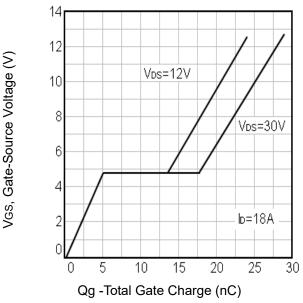


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

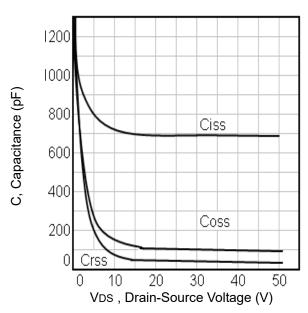


Fig10. Typical Capacitance Vs.Drain-Source Voltage

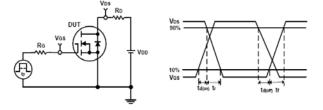
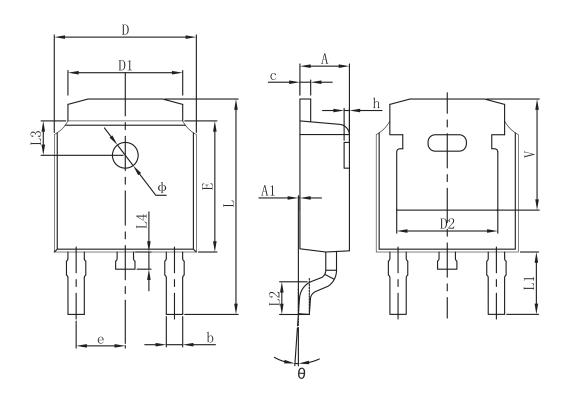


Fig12. Switching Time Test Circuit and waveforms



Packaging information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.635	0.770	0.025	0.030	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 REF.		0.190 REF.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.712	10.312	0.382	0.406	
L1	2.900 REF.		0.114	REF.	
L2	1.400	1.700	0.055	0.067	
L3	1.600 REF.		0.063 REF.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.250	REF.	0.207 REF.		



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